

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Patent Application of: **Kuei-Wu Huang, et al.**

Serial No.: **10/687,713**

Group Art Unit: **1765**

Filed: **October 17, 2003**

Examiner: **L. Vinh**

For: **SURFACE TREATED LOW-K DIELECTRIC AS DIFFUSION BARRIER FOR  
COPPER METALLIZATION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AND RESPONSE**

Sir:

In response to the Office Action of January 6, 2006, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 5 of this paper.